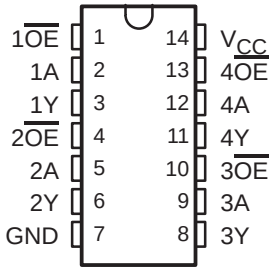
- **Qualification in Accordance With AEC-Q100†**
- **Qualified for Automotive Applications**
- **Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval**
- **Operates From 1.65 V to 3.6 V**
- **Specified From −40°C to 125°C**
- **Inputs Accept Voltages to 5.5 V**
- **Max t_{pd} of 4.8 ns at 3.3 V**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C**

† Contact factory for details. Q100 qualification data available on request.

- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

D OR PW PACKAGE
(TOP VIEW)



description/ordering information

This quadruple bus buffer gate is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVC125A features independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable ($\overline{OE}$) input is high.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

ORDERING INFORMATION

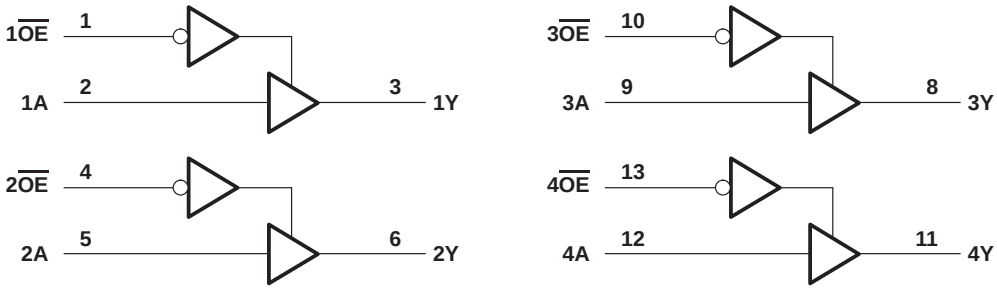
T_A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 125°C	SOIC − D	Reel of 2500	SN74LVC125AQDRQ1	LC125AQ
	TSSOP − PW	Reel of 2000	SN74LVC125AQPWRQ1	LC125AQ

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 6.5 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to 6.5 V
Output voltage range, V_O (see Notes 1 and 2) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0) . . . . . −50 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . −50 mA
Continuous output current, I_O . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±100 mA
Package thermal impedance, θ_{JA} (see Note 3): D package . . . . . 86°C/W
PW package . . . . . 113°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C
Power dissipation, P_{tot} (T_A = −40°C to 125°C) (see Notes 4 and 5) . . . . . 500 mW

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
2. The value of V_{CC} is provided in the recommended operating conditions table.
3. The package thermal impedance is calculated in accordance with JESD 51-7.
4. For the D package: above 70°C, the value of P_{tot} derates linearly with 8 mW/K.
5. For the PW package: above 60°C, the value of P_{tot} derates linearly with 5.5 mW/K.

recommended operating conditions (see Note 6)

			T_A = 25°C		−40 TO 125°C		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	Operating	1.65	3.6	1.65	3.6	V
		Data retention only	1.5		1.5		
V_{IH}	High-level input voltage	V_{CC} = 1.65 V to 1.95 V	0.65 × V_{CC}		0.65 × V_{CC}		V
		V_{CC} = 2.3 V to 2.7 V	1.7		1.7		
		V_{CC} = 2.7 V to 3.6 V	2		2		
V_{IL}	Low-level input voltage	V_{CC} = 1.65 V to 1.95 V		0.35 × V_{CC}		0.35 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V		0.7		0.7	
		V_{CC} = 2.7 V to 3.6 V		0.8		0.8	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 1.65 V		−4		−4	mA
		V_{CC} = 2.3 V		−8		−8	
		V_{CC} = 2.7 V		−12		−12	
		V_{CC} = 3 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 1.65 V		4		4	mA
		V_{CC} = 2.3 V		8		8	
		V_{CC} = 2.7 V		12		12	
		V_{CC} = 3 V		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate			8		8	ns/V

NOTE 6: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C			−40 TO 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
V_{OH}	I_{OH} = −100 μA		1.65 V to 3.6 V	V_{CC}−0.2			V_{CC}−0.2		V
	I_{OH} = −4 mA		1.65 V	1.29			1.1		
	I_{OH} = −8 mA		2.3 V	1.9			1.75		
	I_{OH} = −12 mA		2.7 V	2.2			2.1		
			3 V	2.4			2.35		
	I_{OH} = −24 mA		3 V	2.3			2.1		
V_{OL}	I_{OL} = 100 μA		1.65 V to 3.6 V			0.1		0.2	V
	I_{OL} = 4 mA		1.65 V			0.24		0.45	
	I_{OL} = 8 mA		2.3 V			0.3		0.7	
	I_{OL} = 12 mA		2.7 V			0.4		0.5	
	I_{OL} = 24 mA		3 V			0.55		0.7	
I_I	V_I = 5.5 V or GND		3.6 V			±1		±10	μA
I_{OZ}	V_O = V_{CC} or GND		3.6 V			±1		±10	μA
I_{CC}	V_I = V_{CC} or GND,	I_O = 0	3.6 V			1		20	μA
ΔI_{CC}	One input at V_{CC} − 0.6 V, Other inputs at V_{CC} or GND		2.7 V to 3.6 V			500		500	μA
C_i	V_I = V_{CC} or GND		3.3 V		5				pF

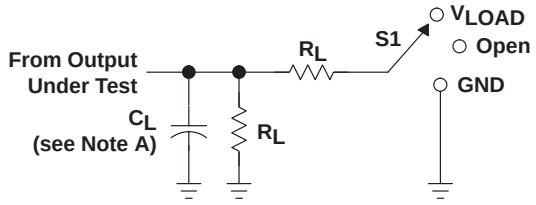
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			−40 TO 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	2.7 V	1	3	5.3	1	7	ns
			3.3 V ± 0.3 V	1	2.5	4.6	1	6	
t_{en}	$\overline{OE}$	Y	2.7 V	1	3.3	6.4	1	8.5	ns
			3.3 V ± 0.3 V	1	2.4	5.2	1	7	
t_{dis}	$\overline{OE}$	Y	2.7 V	1	2.5	4.8	1	6.5	ns
			3.3 V ± 0.3 V	1	2.4	4.4	1	6	
$t_{sk(o)}$			3.3 V ± 0.3 V					1.5	ns

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance per gate	f = 10 MHz	3.3 V	15	pF

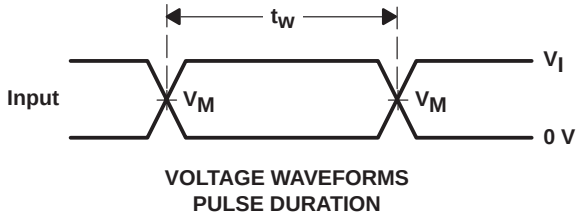
PARAMETER MEASUREMENT INFORMATION



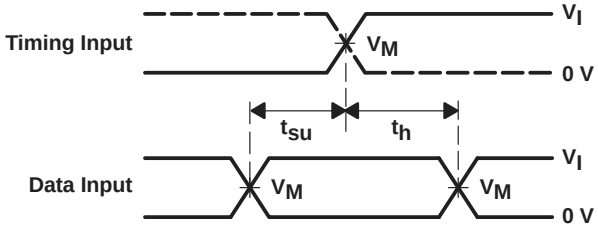
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

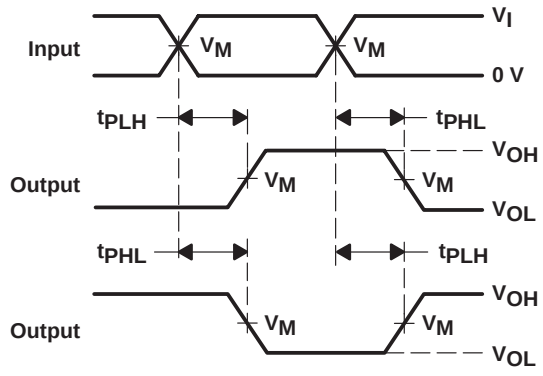
V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
2.7 V	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V ± 0.3 V	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



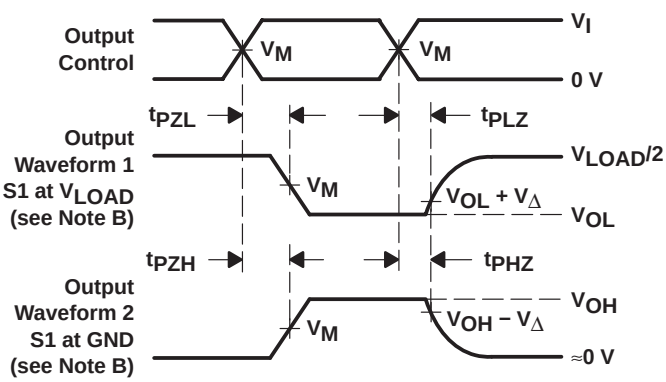
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

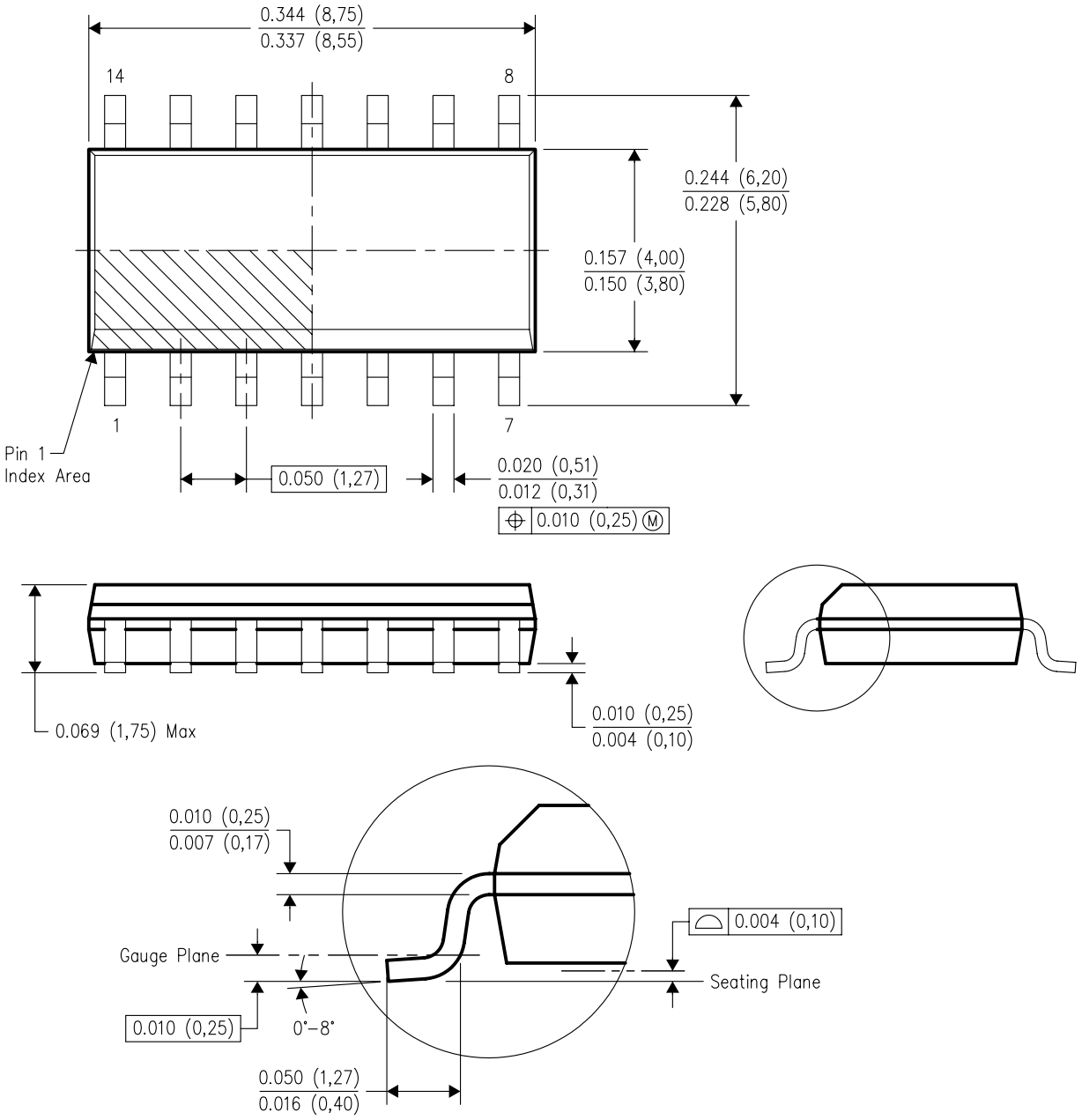


VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.
H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

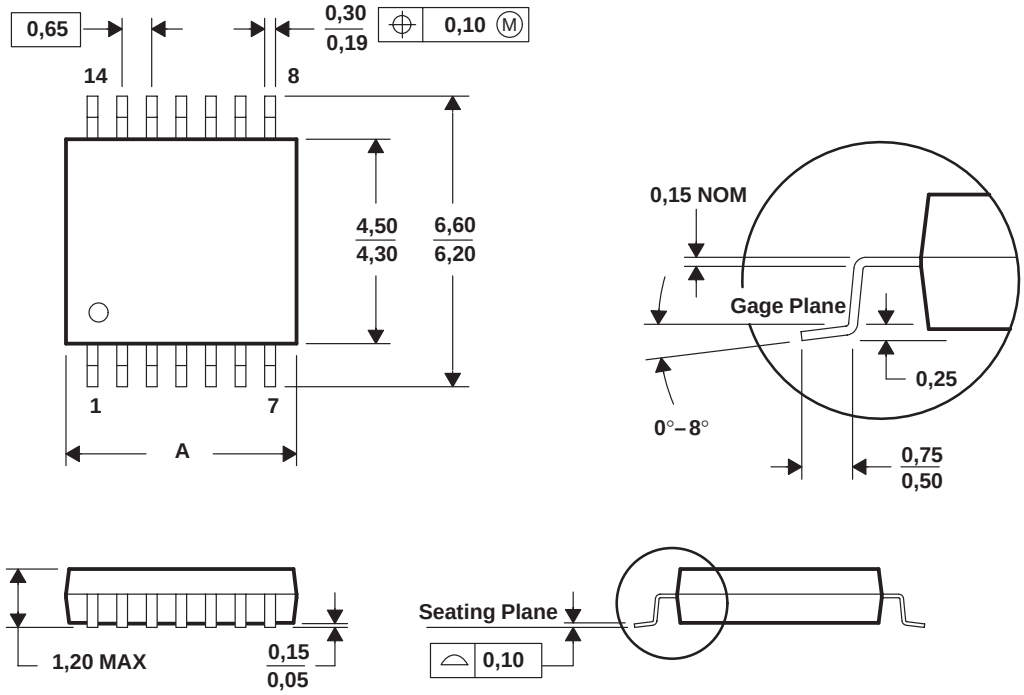
D (R–PDSO–G14) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AB.

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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